

(a) Bookwork but essentially:

- Smooth surfaces
- no friction or adhesion
- linear elasticity
- small strains

$$(b) (i) \quad D = \frac{4}{3} E^* R^{1/2} (\delta - 2\delta_c)(\delta + \delta_c)^{1/2}$$

if  $\delta \gg \delta_c$  then  $D = \frac{4}{3} E^* R^{1/2} \delta^{3/2}$

which is data sheet formula rearranged.

But clearly from inspection of given formula  $D=0$  when  $\delta = 2\delta_c$  or  $\delta = -\delta_c$  so that there is adhesion over range  $-\delta_c < \delta < 2\delta_c$

$$(ii) \quad P = \frac{4}{3} \times 3 \times 10^6 \times (.001)^{1/2} (\delta - 2\delta_c)(\delta + \delta_c)^{1/2}$$

$$\delta_c = \frac{2}{3} (.001)^{3/2} \left( \frac{80 \times 10^{-3}}{3 \times 10^6} \right)^{2/3} = \underline{1.34 \times 10^{-6} \text{ m}}$$

$$P = \frac{4}{3} \times 3 \times 10^6 \times (.001)^{1/2} (\delta - 2.68 \times 10^{-6})(\delta + 1.34 \times 10^{-6})^{1/2}$$

$$\text{or } \underline{P = 126.5 (\delta - 2.68)(\delta + 1.34)^{1/2}} \text{ } \mu\text{N if } \delta \text{ in } \mu\text{m}$$

which is Hertz

$$\underline{P_H = 126.5 \delta^{3/2}}$$

Hence numerical values

-1	$\delta, \mu\text{m}$	-1.34	-1	0	1	1.5	2	2.68	3	4	5	$\delta$
-27	$P, \mu\text{N}$	0	-367	-392	-325	-251	-157	0	84	385	734	$-P$
	$P_H, \mu\text{N}$	-	-	0	127	232	358	555	657	1012	1414	$P_H$

$$(iii) \quad P = \frac{4}{3} E^* R^{1/2} (s - 2s_c) (s + s_c)^{1/2}$$

When  $P=0$  clearly still stable contact with  $s=2s_c$ .

Pull-off will occur when  $\frac{dP}{ds} = 0$

$$\text{But } \frac{dP}{ds} = \frac{4}{3} E^* R^{1/2} \left\{ (s - 2s_c) \frac{1}{2} (s + s_c)^{-1/2} + (s + s_c)^{1/2} \cdot 1 \right\}$$

$$= 0 \quad \text{when} \quad (s - 2s_c) + 2(s + s_c) = 0$$

$$\text{i.e. } 3s = 0, \quad \underline{s = 0}$$

$$\text{then } P = \frac{4}{3} E^* R^{1/2} - 2s_c s_c^{1/2}$$

$$\text{So substituting } s_c = \frac{3}{2} R^{2/3} \left( \frac{W'}{E^*} \right)^{1/3}$$

$$P = -\frac{4}{3} E^* R^{1/2} \cdot 2 \left( \frac{3}{2} \right)^{2/3} R^{2/3} \frac{W'}{E^*} = -\frac{8}{3} \left( \frac{3}{2} \right)^{2/3} R W'$$

$$\text{i.e. } \text{max tensile (orved)} \quad P_{\text{pull-off}} = \underline{4.9 R W'} \\ \text{(equivalent to } 392 \mu\text{N)}$$

$$\text{If this just balances sub weight} = \frac{4}{3} \pi R^3 \rho g$$

$$\frac{4}{3} \pi R^3 \rho g = 4.9 R W'$$

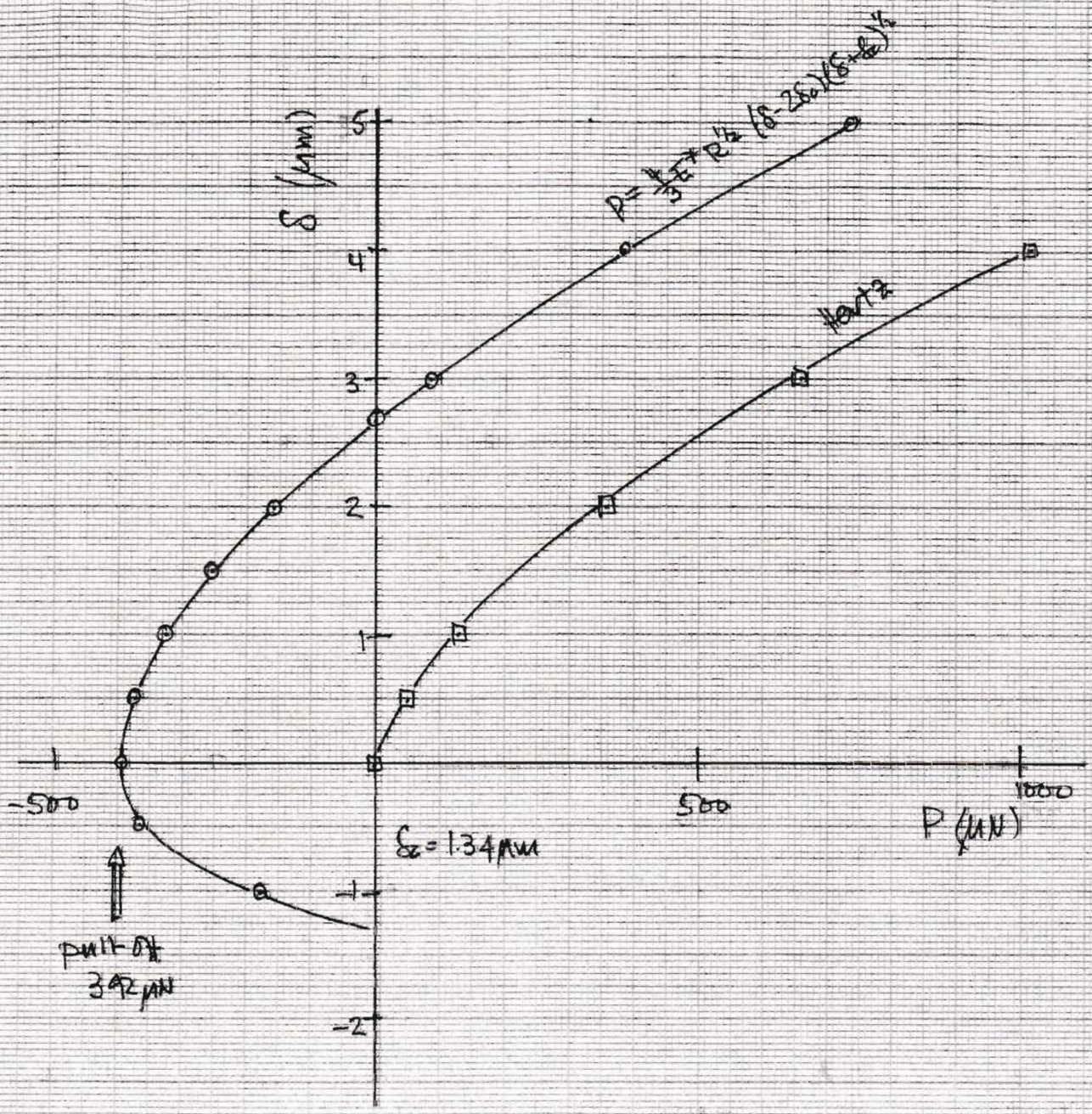
$$R^2 = \frac{4.9 \times 3 W'}{4 \pi \rho g} = \frac{4.9 \times 3 \times 80 \times 10^{-3}}{4 \pi \times 1200 \times 9.81}$$

$$\therefore \underline{R = 2.8 \text{ mm}}$$

(iv) Dirty slide would reduce  $w$  see by reference to values of surface energy in data sheet. So  $R$  falls.

A meniscus film might "improve" adhesion. It's blowing up from pores i.e.  $2\pi R \gamma$   $\gamma = 731 \text{ mJm}^{-2}$

$$2\pi R \gamma = \frac{4}{3} \pi R^3 \rho g \quad \text{So that } R = \sqrt{\frac{3\gamma}{2\rho g}} \\ = \sqrt{\frac{3 \times 731 \times 10^{-3}}{2 \times 1200 \times 9.81}} = 3.1 \text{ mm}$$



Q2

(a)

 $C_{tot} = \text{total capacitance}$ 

$$= C_0(x) \parallel C_1 + C_2$$

$$= \left( \frac{\epsilon_0 A}{g-x} \right) \frac{\epsilon_0 A}{ng} + C_2$$

$$\frac{\epsilon_0 A}{g-x} + \frac{\epsilon_0 A}{ng}$$

$$= \frac{\epsilon_0 A}{[(n+1)g - x]} + C_2$$

$$(b) \quad W = \frac{1}{2} C_{tot} V^2 \quad (\text{stored energy})$$

$$= \frac{1}{2} \left( \frac{\epsilon_0 A}{[(n+1)g - x]} + C_2 \right) V^2$$

$$F_{el} = -\frac{\partial W}{\partial x} \quad (\text{electrostatic force})$$

$$= -\frac{\partial}{\partial x} \left[ \frac{1}{2} \left( \frac{\epsilon_0 A}{[(n+1)g - x]} + C_2 \right) \right] V^2$$

$$= -\frac{1}{2} \frac{\epsilon_0 A V^2}{[(n+1)g - x]^2}$$

$$F_{tot} = F_{el} + F_{mech}$$

$$= -\frac{1}{2} \frac{\epsilon_0 A V^2}{[(n+1)g - x]^2} + kx$$

$$\frac{\partial F_{tot}}{\partial x} = k - \frac{1}{2} \frac{\epsilon_0 A V^2 (2)}{[(n+1)g - x]^3}$$

$$\text{at } x = x_{PI};$$

$$k = \frac{\epsilon_0 A V^2}{[(n+1)g - x_{PI}]^3}$$

$$\text{also } F_{tot} = 0.$$

$$\therefore \frac{\epsilon_0 A V^2}{2[(n+1)g - x_{PI}]^2} = \frac{\epsilon_0 A V^2 x_{PI}}{[(n+1)g - x_{PI}]^3}$$

$$\therefore (n+1)g - x_{PI} = 2x_{PI}$$

$$\text{or } x_{PI} = \frac{(n+1)g}{3}$$

$$\text{as } n \rightarrow 0 \quad x_{PI} \rightarrow g/3.$$

$$(c) \quad \text{For } x_{PI} = g$$

$$\frac{(n+1)g}{3} = g$$

$$\text{or } n+1 = 3$$

$$\Rightarrow n = 2$$

The capacitor  $G$  in series with  $C_0$  must equal half the nominal value of  $C_0$  (to ensure stable operation over the entire gap or less).

Q3 (a)

$$f = \frac{1}{2\pi} \sqrt{\frac{k_{\text{eff}}}{M_{\text{eff}}}} = \frac{1}{2\pi} \sqrt{\frac{\pi^2 E h}{\rho L^2 h}} = \frac{1}{2L} \sqrt{\frac{E}{\rho}}$$

$$E = 160 \text{ GPa}, \quad \rho = 2330 \text{ kg/m}^3$$

$$f = \frac{1}{2 \times 10^{-3}} \times \sqrt{\frac{160 \times 10^9}{2330}} = 4.14 \text{ MHz}$$

$$f = 16 \text{ MHz} \Rightarrow L = \frac{1}{2 \times 10^9} \sqrt{\frac{160 \times 10^9}{2330}} = 4.14 \mu\text{m}$$

Frequency scaling: ① Choose materials with high acoustic velocity  $\sqrt{E/\rho}$  e.g. diamond,

② Reduce dimension  $L$  by lithography. ③ Scale to higher-order modes.

$$(b) \quad k_{\text{eff}} = \pi^2 E h = 15.8 \text{ MN/m}$$

$$M_{\text{eff}} = \rho A h = 2.33 \times 10^{-8} \text{ kg}$$

$$B_{\text{eff}} = \frac{W M_{\text{eff}}}{Q} = 6.06 \times 10^{-6} \text{ N-s/m}$$

$$\eta_{1\text{-port}} = \frac{V_{\text{DC}} \epsilon_0 A_{144}}{g^2} = \frac{100 \times 8.85 \times 10^{-12} \times 10^{-18} \times 4}{10^{-12}} = 4 \times 8.85 \times 10^{-6} \text{ C/V} = 3.54 \times 10^{-5} \text{ C/m}$$

$$\eta_{2\text{-port}} = \frac{V_{\text{DC}} \epsilon_0 A_{12}}{g^2} = \frac{100 \times 8.85 \times 10^{-12} \times 10^{-8} \times 2}{10^{-12}} = 1.77 \times 10^{-5} \text{ C/m}$$

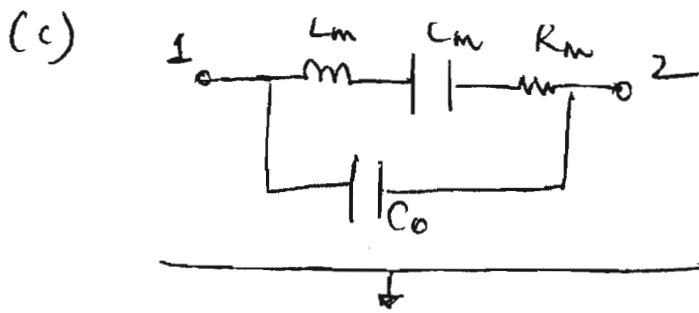
$$(i) \quad 1\text{-port} \quad L_m = \frac{M_{\text{eff}}}{\eta^2} = \frac{2.33 \times 10^{-8}}{(3.54 \times 10^{-5})^2} = 18.6 \text{ H}$$

$$C_m = \frac{\eta^2}{k_{\text{eff}}} = \frac{(3.54 \times 10^{-5})^2}{15.8 \times 10^6} = 7.93 \times 10^{-17} \text{ F}$$

$$R_m = \frac{B_{\text{eff}}}{\eta^2} = \frac{6.06 \times 10^{-6}}{(3.54 \times 10^{-5})^2} = 4835 \Omega$$

(ii) 2-port values are given by:

$$L_m = 4 \times 18.6 = 74.4 \text{ H}; \quad C_m = 4 \times 7.93 \times 10^{-17} \text{ F}; \quad R_m = 4 \times 4835 \Omega$$



$$Y_m(j\omega) = j\omega C_0 + \frac{j\omega C_m}{\left[1 - (\omega/\omega_0)^2\right] + j\omega/\omega_0 Q}$$

is the expression for admittance

(d)

$$f_{res} = \frac{1}{2L} \sqrt{\frac{E}{\rho}}$$

$$\frac{df_{res}/f_{res}}{dT} \approx \frac{1}{2} \frac{dE/E}{dT} \quad \text{as } \frac{(dL/L)}{dT} \text{ is considered small for polysilicon by about an order of magnitude}$$

Approaches to passive temperature compensation include:

- ① Degenerate doping
- ② Coating the resonator with a material describing opposite dependence of  $\epsilon$  on  $T$  e.g.  $\text{SiO}_2$  or embedding  $\text{SiO}_2$  pillars in polysilicon
- ③ Temperature compensation by inducing mechanical stress in the resonator in a well-defined manner as a function of temp to compensate for inherent dependence.

$$\begin{aligned} \textcircled{4} \textcircled{a} \quad \Delta C &= \frac{C_s}{g} \left[ \frac{g}{g-x} - \frac{g}{g+x} \right] \\ &\approx C_s \cdot \frac{2xg}{g^2} \\ &= C_s \left( \frac{2x}{g} \right) \end{aligned}$$

$$x = \frac{ma}{k} = \frac{a}{\omega_r^2}$$

$$\frac{\Delta C}{C_s} = 2 \left( \frac{a}{\omega_r^2} \right) \cdot \frac{1}{g}$$

$$\textcircled{b} \quad \overline{x_n^2} = \frac{4k_B T b}{k^2}$$

$$\overline{a_n^2} = \frac{k^2}{m^2} \overline{x_n^2} = \frac{4k_B T b}{m^2}$$

$$\text{min. det. acceleration} \approx \frac{2 \sqrt{4k_B T b}}{m} \approx \frac{4 \sqrt{k_B T b}}{m}$$

m 1Hz BW

$$\textcircled{c} \quad \overline{a_n^2} = \frac{4k_B T b}{m^2} = \frac{4k_B T \omega_0 m}{m^2 Q} = \frac{4k_B T \omega_0}{m Q}$$

$$\begin{aligned} \text{min. detectable acceleration} &= 4 \sqrt{\frac{k_B T \omega_0}{m Q}} \\ &= 4 \sqrt{\frac{1.38 \times 10^{-23} \times 300 \times 2\pi \times 10^3}{10^{-6} \times 10}} \\ &= 6.45 \text{ } \mu\text{m/s}^2 / \sqrt{\text{Hz}} \end{aligned}$$

$$\textcircled{d} \quad \left( \frac{\Delta C}{C_s} \right) = 2 \left( \frac{a}{\omega_r^2} \right) \cdot \frac{1}{g}$$

$$\therefore a_{\text{min}} = \left( \frac{\Delta C}{C_s} \right)_{\text{min}} \cdot \frac{\omega_r^2 g}{2} = \frac{10^{-6} \times (2\pi \times 10^3)^2 \times 10^{-6}}{2} = 19.7 \text{ } \mu\text{m/s}^2$$



(e) Design approaches to reduce minimum detectable noise floor include -

- better resolution of capacitance changes
- reduce noise of interface circuit for capacitance measurement
- reduce natural frequency ( $\uparrow$  sensitivity)
- decrease capacitive gap (if electronic noise limits)
- increase proof mass (larger area or more complex process)
- reduce damping (e.g. by vacuum packaging)
- reduce temperature (e.g. by active cooling)